

Edition 1.0 2007-08

INTERNATIONAL STANDARD

Electronics assembly technology - Electronic modules

(https://standards.iteh.ai)
Document Preview

IEC 62421:2007

https://standards.iteh.ai/catalog/standards/iec/d4456ebd-f4ea-4f72-aa81-e29dced0966d/iec-62421-2007





THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2007 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester.

If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

IEC Central Office 3, rue de Varembé CH-1211 Geneva 20 Switzerland

Email: inmail@iec.ch Web: www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigenda or an amendment might have been published.

- Catalogue of IEC publications: <u>www.iec.ch/searchpub</u>
- The IEC on-line Catalogue enables you to search by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, withdrawn and replaced publications.
- IEC Just Published: www.iec.ch/online news/justpub
- Stay up to date on all new IEC publications. Just Published details twice a month all new publications released. Available on-line and also by email.
- Electropedia: www.electropedia.org
- The world's leading online dictionary of electronic and electrical terms containing more than 20 000 terms and definitions in English and French, with equivalent terms in additional languages. Also known as the International Electrotechnical Vocabulary online.
- Customer Service Centre: www.iec.ch/webstore/custserv
 If you wish to give us your feedback on this publication or need further assistance, please visit the Customer Service Centre FAQ or contact us:

Email: csc@iec.ch

nttTel.: +41 22 919 02 11 /catalog/standards/jec/d4456ebd- [4ea-4[72-aa8]-e29dced0966d/jec-6242]-2007

Fax: +41 22 919 03 00



Edition 1.0 2007-08

INTERNATIONAL STANDARD

Electronics assembly technology – Electronic modules

(https://standards.iteh.ai)
Document Preview

IEC 62421:2007

https://standards.iteh.ai/catalog/standards/iec/d4456ebd-f4ea-4f72-aa81-e29dced0966d/iec-62421-2007

INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRICE CODE

P

CONTENTS

FO	REW	ORD		4	
1	Scop	e and c	object	6	
2		ormative references6			
3	Terms and definitions				
4 Business model and interface between supplier and user					
4			• •		
	4.1		ess model (see Figure 1 and Figure 2)		
		4.1.1	General		
		4.1.2 4.1.3	E-type business model		
		4.1.3	F-type business model		
	4.2		terface (see Figure 1)		
	4.2	4.2.1	S-U interface –1		
		4.2.1	S-U interface = 2		
		4.2.3	S-U interface–3	_	
	4.3		ardization areas	_	
5			tings		
Ü	5.1		al iTah Standards		
	5.2		red operating temperature range		
	5.3	(https://stondowedgitab.gi)			
6			neasuring methods		
Ū	6.1	Standard atmospheric conditions		11	
	0.1	6.1.1	Standard atmospheric conditions for testing		
		6.1.2	Referee conditions		
		6.1.3	Reference conditions		
	6.2	Electrical performance tests			
	0.2	6.2.1	General		
		6.2.2	Protection of electronic modules and test equipment		
		6.2.3	Accuracy of measurement		
	6.3	Mecha	anical performance tests		
		6.3.1	Robustness of terminations and integral mounting devices		
		6.3.2	Resistance to soldering heat	14	
		6.3.3	Solderability	14	
		6.3.4	Shock	14	
		6.3.5	Vibration (sinusoidal)	14	
		6.3.6	Resistance to solvents	15	
	6.4	Climat	tic performance tests	15	
		6.4.1	Dry heat	15	
		6.4.2	Cold	15	
		6.4.3	Damp heat, steady state	16	
		6.4.4	Change of temperature	16	

Figure 1 – S-U interfaces in each business model	8
Figure 2 – Standardization areas in M-type and F-type business models	10
Table 1 – Preferred temperatures to be selected for temperature ranges (°C)	11
Table 2 – Referee conditions	12
Table 3 – Application	14

iTeh Standards (https://standards.iteh.ai) Document Preview

IEC 62421:2007

https://standards.iteh.ai/catalog/standards/iec/d4456ebd-f4ea-4f72-aa81-e29dced0966d/iec-62421-2007

INTERNATIONAL ELECTROTECHNICAL COMMISSION

ELECTRONICS ASSEMBLY TECHNOLOGY – ELECTRONIC MODULES

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 62421 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/689/FDIS	91/722/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- · reconfirmed;
- withdrawn;
- · replaced by a revised edition, or
- · amended.

A bilingual version of this publication may be issued at a later date.

iTeh Standards (https://standards.iteh.ai) Document Preview

IEC 62421:2007

https://standards.iteh.ai/catalog/standards/iec/d4456ebd-f4ea-4f72-aa81-e29dced0966d/iec-62421-2007

ELECTRONICS ASSEMBLY TECHNOLOGY – ELECTRONIC MODULES

1 Scope and object

This International Standard provides a generic standard of electronic modules on which their sectional standards are based.

This standard provides a definition, business model, interface between the trading partners, and related areas of standardization of electronic modules. In addition a generic set of test method is provided.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068 (all parts), Environmental testing

IEC 60068-1:1988, Environmental testing - Part 1: General and guidance

IEC 60068-2-1: Environmental Testing - Part 2-1: Tests - Test A: Cold

IEC 60068-2-2: Environmental testing - Part 2-2: Tests - Tests B: Dry heat

IEC 60068-2-6: Environmental testing – Part 2-6: Tests – Test Fc: Vibration (sinusoidal)

IEC 60068-2-14: Environmental testing – Part 2-14: Tests – Test N: Change of temperature

IEC 60068-2-20: Environmental testing - Part 2-20: Tests - Test T: Soldering

IEC 60068-2-21: Environmental testing – Part 2-21: Tests – Test U: Robustness of terminations and integral mounting devices

IEC 60068-2-27: Environmental testing - Part 2-27: Tests - Test Ea and guidance: Shock

IEC 60068-2-45: Environmental testing – Part 2-45: Tests – Test XA and guidance: Immersion in cleaning solvents

IEC 60068-2-58: Environmental testing — Part 2-58: Tests — Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

IEC 60068-2-78: Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state

ISO 3: Preferred numbers - Series of preferred numbers

3 Terms and definitions

For the purposes of this document, the terms and definitions given in the IEC 60068 series, as well as the following, apply.

3.1

electronic module

functional block which contains individual electronic elements and /or electronic packages, to be used in a next level assembly

NOTE An individual module having an application-specific function, including electronic, optoelectronic, mechanical or other elements. The module typically provides protection of its elements and packages to assure the required level of reliability.

Electronic modules may be categorized by signal interface, for example:

- wired module: a module which has only electrical interfaces (majority of present day modules)
- wireless module: a module which has a wireless interface
- opto-electronic module: a module which has an optoelectronic interface
- sensor module: a module which can input physical information
- actuator module: a module which could output physical information

3.2

coplanarity

distance in height between the lowest and highest leads or terminals when the module is in its seating plane

3.3

operating temperature range

range of the ambient temperature at which an electronic module may be used continuously

3.4

storage temperature range

range of the ambient temperature at which an electronic module may be stored continuously

3.5

rated voltage

maximum d.c. voltage or the root-mean square value of an a.c. voltage which may be applied continuously to an electronic module at any temperature within the operating temperature range

4 Business model and interface between supplier and user

4.1 Business model (see Figure 1 and Figure 2)

4.1.1 General

Business models for electronic module manufacturing are classified into three types (See Figure 1):

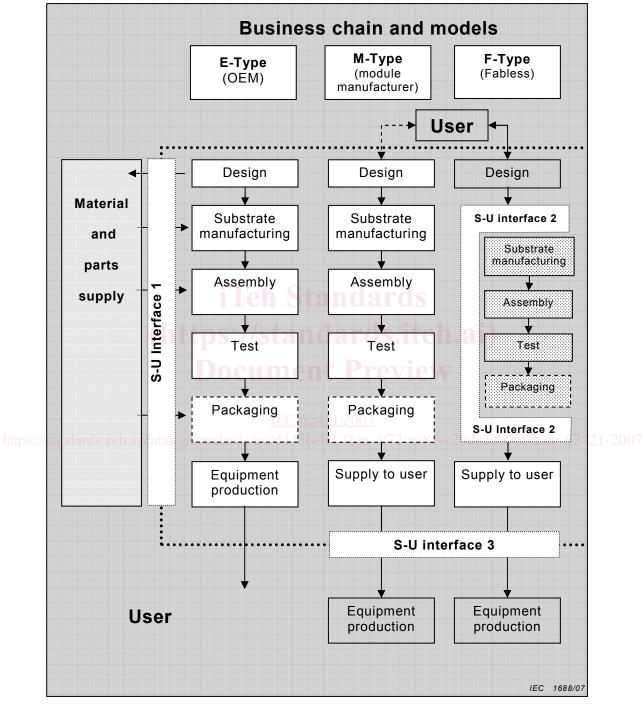
- E-type;
- M-type;
- F-type business models.

A supplier of material/parts is at one end of a business chain, from the viewpoint of an electronic module supplier. A user of electronic modules is at the other end of the chain.

Items to be specified in standards of electronic modules depend on the business model to which the relevant module is classified.

Items to be standardized basically depend on the relationship between suppliers and users (S-U Interface). Moreover, the S-U Interface depends on the business model.

The S-U interface showing the relationship between suppliers and users shall be clarified in the scope of a standard for an electronic module.



NOTE S-U interface: Supplier and user interface.

Figure 1 - S-U interfaces in each business model

4.1.2 E-type business model

The user of the electronic modules is also the supplier of the electronic modules. (The modules are designed, manufactured and used within the same company.)